

HT7000 Thermal Conductive Gap Filler

BENEFITS AND FEATURES

- Easily dispensable and reworkable
- High thermal conductivity and low thermal impedance
- High compressibility for low stress applications
- No pump out and cracking risk
- Proven long term reliability

OVERVIEW

Honeywell HT7000 is one-part, dispensable thermal gap filler with highly thermal conductivity. This material is formulated to balance the dispense rate, long term reliability and reworkable. With its high compressibility, it is designed to minimize thermal resistance at interfaces and maintain excellent performance through reliability testing.

TYPICAL APPLICATIONS

- Telecommunications
- Consumer Electronics
- Automotive electronics
- Memory & power modules

STORAGE & USE

- Shelf life 12 months at 0-35°C, ≤65% RH

Reliability Test (JESD22-A104C)

Thermal Cycling –B (1000cycles)

Property	HT7000	Test Method
Feature	Silicone-based	-
	Pre-cured	-
Color	Red	Visual
Thermal Conductivity (W/m·K)	7.0	ASTM D5470
Thermal Impedance (°C·In ² /W) (1mm@10psi, Typical Value)	0.21	ASTM D5470
Dispense Rate (g/min)	18	90psi, 30cc EFD syringe
Density(g/cm ³)	3.50	ASTM D792
Minimum BLT (μm)	190	HON Internal
Volatile Content (TML%)	<0.05	HON Internal
Volatile Content (CVCM%)	<0.02	HON Internal
Dielectric Strength (KV/mm)	7	ASTM D149
Flammability Rating	V-0(Equivalent)	UL 94
Operating Temperature (°C)	-40~150	HON Internal

*Typical property data values should not be used as specifications

Honeywell Electronic Materials

USA: 1-509-252-2102
 China: 400-840-2233
 Germany: 49-5137-999-9199
 Japan: 81-3-6730-7092
 Korea: 82-2-3483-5076
 Singapore: 65-6580-3593

Although all statements and information contained herein are believed to be accurate and reliable, they are presented without guarantee or warranty of any kind, express or implied. Information provided herein does not relieve the user from the responsibility of carrying out its own tests and experiments, and the user assumes all risks and liability for use of the information and results obtained. Statements or suggestions concerning the use of materials and processes are made without representation or warranty that any such use is free of patent infringement and are not recommendations to infringe any patent. The user should not assume that all toxicity data and safety measures are indicated herein or that other measures may not be required.

DS.0318Rev3
 ©2022 Honeywell International Inc.